To:

Technology Center: 2815

Facsimile Number: 703-872-9306

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AUG 3 0 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Andrew Marshall

Serial No.:

10/007,332

Filed: For:

8-Nov-01

Thermal Coupling of Matched SOI Device Bodies

TI-31484

Art Unit: 2815

Examiner: Warren, M.E.

Conf. No.: 3238

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:

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FACSIMILE COVER SHEET

NEW APPLICATION EOT (# Page DECLARATION (# Pages) NOTICE OF APPEAL (# Page ASSIGNMENT (# Pages) APPEAL (# Page ASSIGNMENT (# Pages) ISSUE FEE (# Pages) INFORMAL DRAWINGS ISSUE FEE (# Pages) REPLY BRIEF (IN TRIPLIC CONTINUATION APP'N (# Pages) DIVISIONAL APP'N		EOT (# Page) NOTICE OF APPEAL (# Pages) APPEAL (# Pages)
NAME OF INVENTOR(S):		RECEIPT DATE & SERIAL NO.:
Andrew Marshall		Serial No.: 10/007,332
TITLE OF INVENTION:		Filing Date: November 8, 2001
Thermal Coupling of Matched SOI Device Bodies THELE NO: DEPOSIT ACCT. NO.:		
TI-31484	20-0668	
FAXED: 8/30/04		
DUE: 9/26/04		
ATTY/SEC'Y:	RAK/reb	

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> Texas Instruments Incorporated PO Box 655474, M/S 3999 Dallas, TX 75265

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AUG 3 0 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Andrew Marshall

Docket No.: TI-31484

Serial No.: 10/007,332

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Filed: 11/08/01

Examiner: Warren, M. E.

Title: Thermal Coupling of Matched SOI Device Bodies

REPLY UNDER 37 C.F.R. §1.116 – EXPEDITED PROCEDURE TECHNOLOGY CENTER 2800

August 30, 2004

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 CERTIFICATION OF FAX TRANSMITTAL

I hereby certify that the above correspondence is being facsimile transmitted to the Patent and Trademark Office on August 30, 2004.

Pohin F Ramum

OK TO ENTER: /MW/ (05/12/2008)

Dear Sir:

In response to the Office Action, dated 07/26/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.